## AMENDMENTS TO THE CLAIMS

1. (Currently Amended) A silicone rubber adhesive composition used for forming an integrally molded article with a thermoplastic ~~an organic~~ resin comprising

(A) 100 parts by weight of a heat curable organopolysiloxane composition,

(B) 1 to 100 parts by weight of reinforcing silica fines, and

(C) 0.1 to 50 parts by weight of an organic compound or organosilicon compound having an epoxy equivalent of 100 to 5,000 g/mol and containing at least one aromatic ring in a molecule

wherein a ~~the~~ cured product of said silicone rubber adhesive composition ~~providing~~ provides a greater bond strength to said thermoplastic ~~organic~~ resin than any metal mold used for forming the integrally molded article.

2. (Previously presented) The composition of claim 1 wherein compound (C) is an organosilicon compound containing at least one Si-H group in a molecule.

3. (Currently Amended) The composition of claim 1 which provides a greater bond strength to organic thermoplastic ~~organic~~ resins than to steel ~~metals~~.

4. (Original) An integrally molded article comprising a silicone rubber adhesive composition in the cured state and a thermoplastic resin, said silicone rubber adhesive composition comprising

(A) 100 parts by weight of a heat curable organopolysiloxane composition,

(B) 1 to 100 parts by weight of reinforcing silica fines, and

(C) 0.1 to 50 parts by weight of an organic compound or organosilicon compound having an epoxy equivalent of 100 to 5,000 g/mol and containing at least one aromatic ring in a molecule.

5. (Previously presented) An integrally molded article comprising a silicone rubber adhesive composition in the cured state and a thermoplastic resin, said silicone rubber adhesive composition comprising:

(A) 100 parts by weight of a heat curable organopolysiloxane composition,

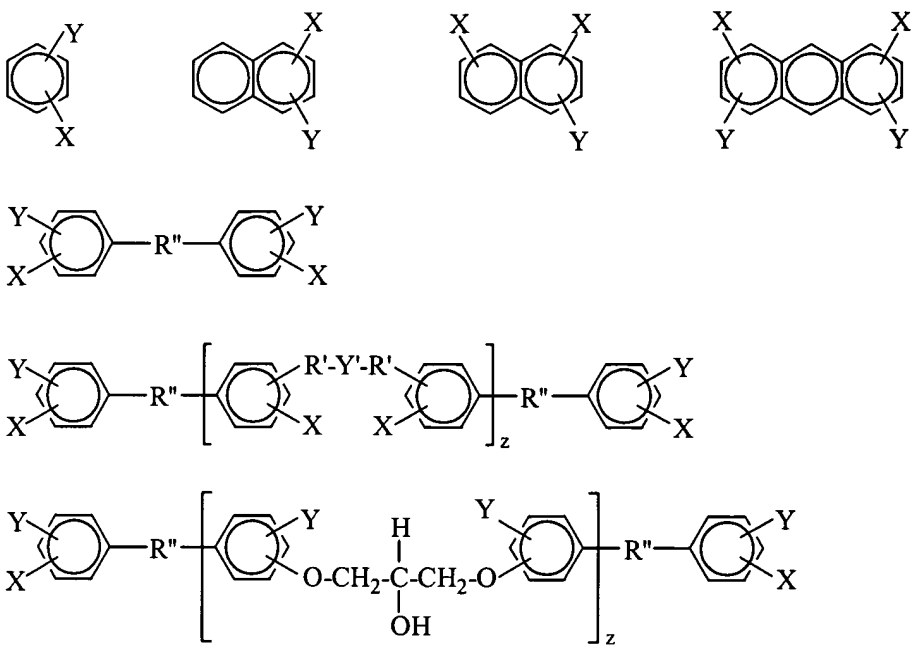
(B) 1 to 100 parts by weight of reinforcing silica fines, and

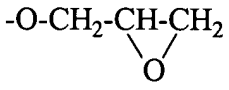
(C) 0.1 to 50 parts by weight of an organic compound or organosilicon compound having an epoxy equivalent of 100 to 5,000 g/mol and containing at least one aromatic ring in a molecule

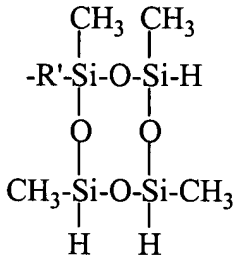
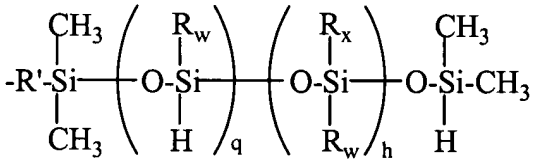
wherein compound (C) is an organosilicon compound containing at least one Si-H group in a molecule.

6. (Currently Amended) The composition of claim 1 wherein ~~compound (C) is~~ the organosilicon compound has ~~having~~ at least one linear or cyclic siloxane structure.

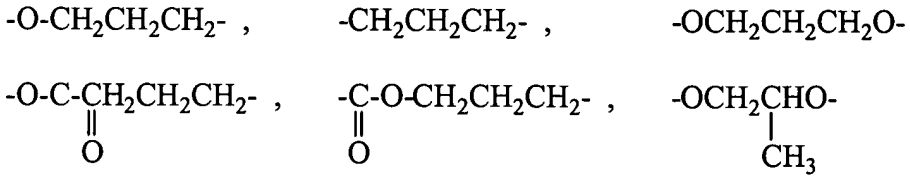
7. (Currently Amended) The composition of claim 1 or wherein compound (C) is at least one selected from the compounds of the following formulae:



wherein X is  ,

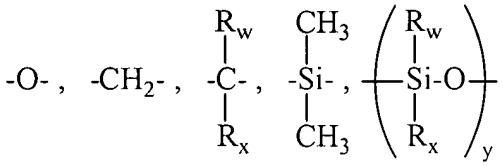
Y is  or 

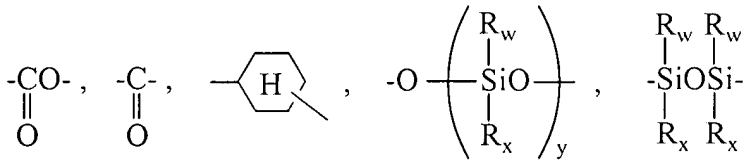
wherein R' is selected from the following groups:



Rw and Rx are substituted or unsubstituted monovalent hydrocarbon groups, q is a number of 1 to 50, and h is a number of 0 to 50,

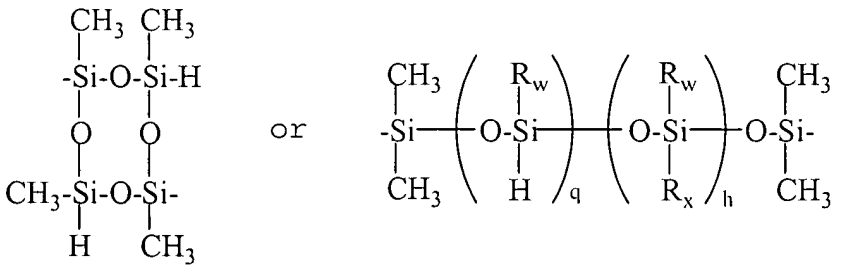
R" is selected from the following groups:





wherein Rw and Rx are as defined above, and y is a number of 0 to 100, and

Y' is



wherein Rw, Rx, q and h are as defined above, and Subscript z is a number of 1 to 10.

8. (Previously presented) The composition of claim 1 wherein the organopolysiloxane composition comprises a diorganopolysiloxane of a straight chain structure whose backbone comprises recurring diorganosiloxane units of the formula: $R^1_2SiO_{2/2}$ and which is blocked with a triorganosiloxy group of the formula: $R^1_3SiO_{1/2}$ at either end

wherein $R^1$ is a substituted or unsubstituted monovalent hydrocarbon group of 1 to 12 carbon atoms.

9. (Previously presented) The composition of claim 1 wherein the organopolysiloxane composition comprises a diorganopolysiloxane has a weight average degree of polymerization of about 10 to 10,000.

10. (New) A silicone rubber adhesive composition used for forming an integrally molded article with a thermoplastic resin comprising:

(A) 100 parts by weight of a heat curable organopolysiloxane composition,

(B) 1 to 100 parts by weight of reinforcing silica fines, and

(C) 0.1 to 50 parts by weight of an organic compound or organosilicon compound having an epoxy equivalent of 100 to

5,000 g/mol and containing at least one aromatic ring in a molecule.